

FZ-2100

- **Out line:** FZ-2100 is a un-filled polyphenylene sulfide resin which is excellent ductility and flexibility.
- **Color:** Black

Engineering Properties of FZ-2100

Properties	Test Method	Unit	FZ-2100
General Information		<ASTM>	Un-reinforced
Physical			
Specific gravity	D-792	-	1.35
Water absorption, 23deg. /24Hrs. /in water	D-570	Wt. %	0.02
Mold shrinkage, MD /TD ^a	D-955	%	1.3/1.5
Mechanical			
Tensile strength	D-638	MPa	80
Tensile modulus	D-638	MPa	4200
Tensile elongation at break	D-638	%	>15
Poisson's ratio	-	-	0.38
Flexural strength	D-790	MPa	130
Flexural modulus	D-790	MPa	3800
Flexural elongation at break	D-790	%	>30
Izod impact strength	D-256	J/m	
notched / un notched			40/1800
Compressive strength	D-695	MPa	120
Rockwell hardness, R/M	D-785	-	121/100
Coefficient of friction ^b , static /dynamic	-	-	0.35/0.40
Thermal			
Distortion temp. of under load, 1.82MPa	D-648	°C	110/200 ^e
Coefficient of thermal expansion ^c , -30 to 90°C	D-696	m/mK	4.0x10 ⁻⁵
UL Flammability ^d , t~0.8mm	UL-94	-	V-0
Electrical			
Dielectric strength, t=1.6mm	D-149	kv/mm	23
Dielectric constant, 1MHz	D-150	-	3.3
Dissipation factor, 1MHz	D-150	-	0.002
Comparative tracking index (CTI)	D-3638	Volt	135
Arc resistance	D-495	sec.	125
Volume resistibility	D-257	Ohm.cm	10 ¹⁶
Process Conditions			
Cylinder temperature	-	°C	300-340
Mold temperature	-	°C	120-150

a: MD; Mold direction, TD; Transverse direction, b: P=150KPa, V=0.3m/s, PPS vs. carbon steel, c: Average value of MD & TD, d: UL file No. E53829, e: Fiber stress 0.46MPa.



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